



Artificial Intelligence with Creativity in Smart Computing and Internet of Things Design

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Message from the Guest Editors

Artificial intelligence has been the focus of global research in recent years. This field, which includes the intelligence of computer computation, has significantly enhanced the stability of automated production in factories. It is a key measure for improving service quality by merging factory production and manufacturing. However, due to its widespread application across various sectors, there is a need for research in related areas that include network transmission, cloud computing, edge computing, and other software and hardware communication layers. This Special Issue aims to address the technical challenges associated with the distributed computing of numerous devices.

Topics of interest include, but are not limited to:

- Federated learning and edge computing in artificial intelligence;
- Data collection and analysis in intelligent computing;
- Optimizing resource allocation and management;
- Computer vision and creative computing;
- Intelligent Internet of Things with edge/cloud computing;
- Intelligent system;
- Other research issues about smart computing and the Internet of Things.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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